Claim Amendments

1-14 (Canceled)

15. (Currently Amended) A head gimbal assembly comprising:

a suspension;

a head interconnect circuit being attached to and disposed along the suspension, the head interconnect circuit including a first conductive material; and

a slider comprising a top, a bottom; and

a flex circuit having a first and second surface, wherein the first surface is opposite the second surface, further wherein the first surface attached to the top of the slider, and at least one interconnect pad is disposed on the second surface of the flex circuit in an area between the slider and the suspension for providing electrical contact with the conductive material of the head interconnect circuit.

16. (Previously Presented) The head gimbal assembly of claim 15, wherein the slider includes a front end and at least one bond pad disposed on the front end, and the flex circuit further includes a second conductive material extending between the at least one bond pad and the at least one interconnect pad, and the conductive material of the flex circuit is electrically connected to the at least one interconnect pad and to the at least one bond pad.

17. (Currently Amended) The head gimbal assembly of claim 16, wherein the slider includes first, second, third, and fourth interconnect pads disposed on the ~~back~~ second surface of the flex circuit ~~slider~~, and first, second, third, and fourth bond pads disposed on the front end of the slider, wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pads, and the at least one bond pad is one of the first, second, third or fourth bond pads.

18. (Currently Amended) The head gimbal assembly of claim 17, wherein the first and second bond pads are electrically coupled to a first pair of positive and negative polarities of the slider~~/MR head~~ for reading data, respectively, and the third and

fourth bond pads are electrically coupled to a second pair of positive and negative polarities of the slider~~AMR head~~ for writing data, respectively, and the first, second, third, and fourth interconnect pads are arranged such that the polarities of the bond pads match with polarities from the interconnect pads.

19-33 (Canceled)

34. (Currently Amended) A head gimbal assembly comprising:

a suspension, the suspension having a plurality of first conductive material;

a slider having a top and a bottom;

a polymer flex circuit having a first and second surface, wherein the first surface is positioned on the top of the slider and the second surface is positioned opposite of the first surface, further[,] wherein the polymer flex circuit has a plurality of second conductive material positioned on the second surface; and

at least one interconnect pad disposed between the plurality of first conductive material and the plurality of second conductive material to establish an electrical connection.

35. (Previously Presented) The head gimbal assembly of claim 34, wherein the slider further includes at least one bond pad, wherein the bond pad provides for an electrical connection to a transducer positioned in the slider.

36. (Previously Presented) The head gimbal assembly of claim 35, wherein said plurality of second conductive material extends and is electrically connected to said bond pad.

37. (Previously Presented) The head gimbal assembly of claim 35, wherein the slider further includes a front end, further wherein said bond pad is positioned on said front end.

38. (Currently Amended) The head gimbal assembly of claim 35, wherein the slider includes first, second, third, and fourth interconnect pads disposed on the back of the slider~~AMR head~~, and first, second, third, and fourth bond pads disposed on the

front end of the slider~~/MR head~~, wherein the at least one interconnect pad is one of the first, second, third or fourth interconnect pads, and the at least one bond pad is one of the first, second, third or fourth bond pads.

39. (Currently Amended) The head gimbal assembly of claim 38, wherein the first and second bond pads are electrically coupled to a first pair of positive and negative polarities of the slider~~/MR head~~ for reading data, respectively, and the third and fourth bond pads are electrically coupled to a second pair of positive and negative polarities of the slider~~/MR head~~ for writing data, respectively.

40. (Previously Presented) The head gimbal assembly of claim 39, wherein the first, second, third, and fourth interconnect pads are arranged such that the polarities of the bond pads match with polarities of the interconnect pads.

41. (Previously Presented) The head gimbal assembly of claim 40, wherein the first and second interconnect pads are electrically connected to the first and second bond pads of the slider, respectively, and the third and fourth interconnect pads are electrically connected to the third and fourth bond pads of the slider, respectively.